

Reverse Voltage – 50V~1000 V

Forward Current – 2.0 A

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View
 Marking Code: U2AB~U2MB
 Simplified outline SMBF symbol

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US2ABF	US2BBF	US2DBF	US2GBF	US2JBF	US2KBF	US2MBF	Units				
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V				
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V				
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V				
Maximum Average Forward Rectified Current at $T_a = 65^{\circ}\text{C}$	$I_{F(AV)}$	2							A				
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	55				50							
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.0		1.3		1.6		V					
Maximum DC Reverse Current $T_a = 25^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 125^{\circ}\text{C}$	I_R	5 100							μA				
Typical Junction Capacitance ¹⁾	C_J	60							pF				
Maximum Reverse Recovery Time ²⁾	t_{rr}	50				75							
Typical Thermal Resistance ³⁾	R_{JA} R_{JL}	60 20							$^{\circ}\text{C}/\text{W}$				
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^{\circ}\text{C}$				

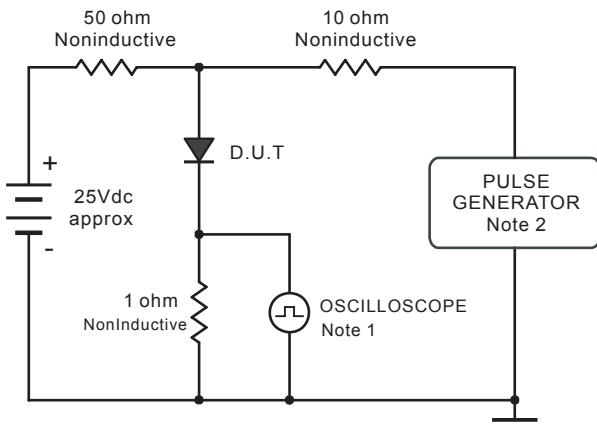
1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Measured with $IF = 0.5 \text{ A}$, $IR = 1 \text{ A}$, $Irr = 0.25 \text{ A}$

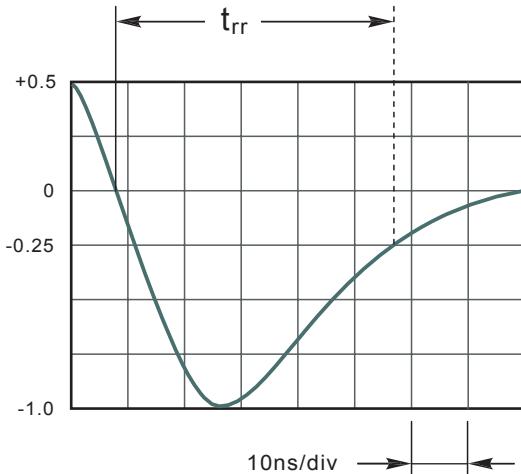
3) P.C.B. mounted with $0.5 \times 0.5"$ ($12.7 \times 12.7 \text{ mm}^2$) copper pad areas.

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Ries Time = 10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

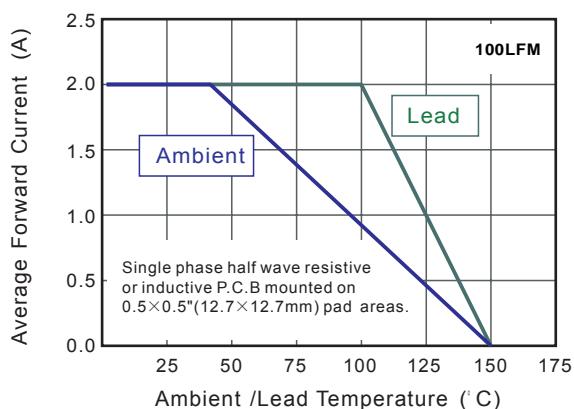


Fig.3 Typical Instantaneous Forward Characteristics

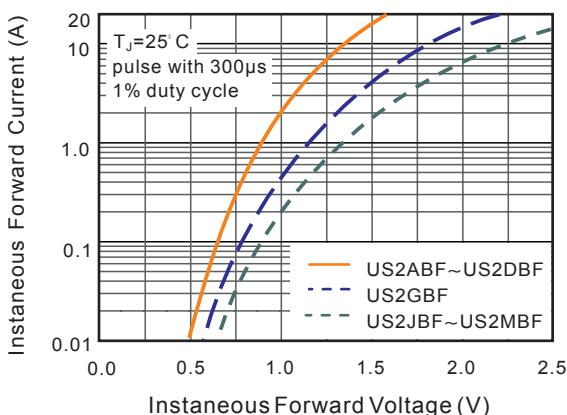


Fig.3 Typical Reverse Characteristics

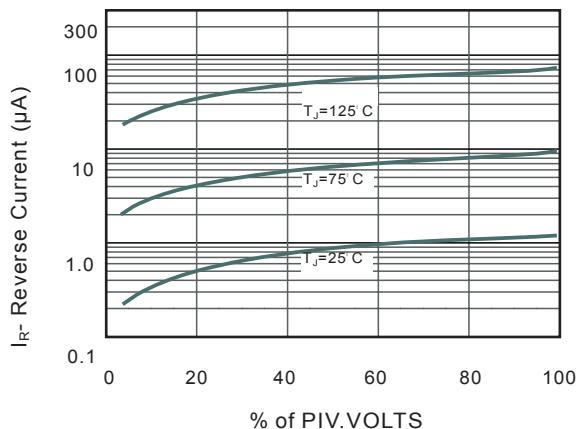
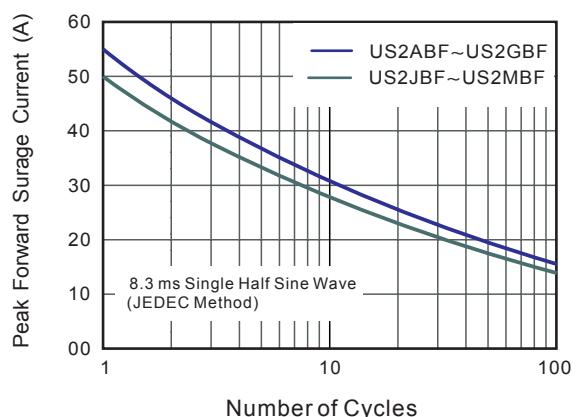


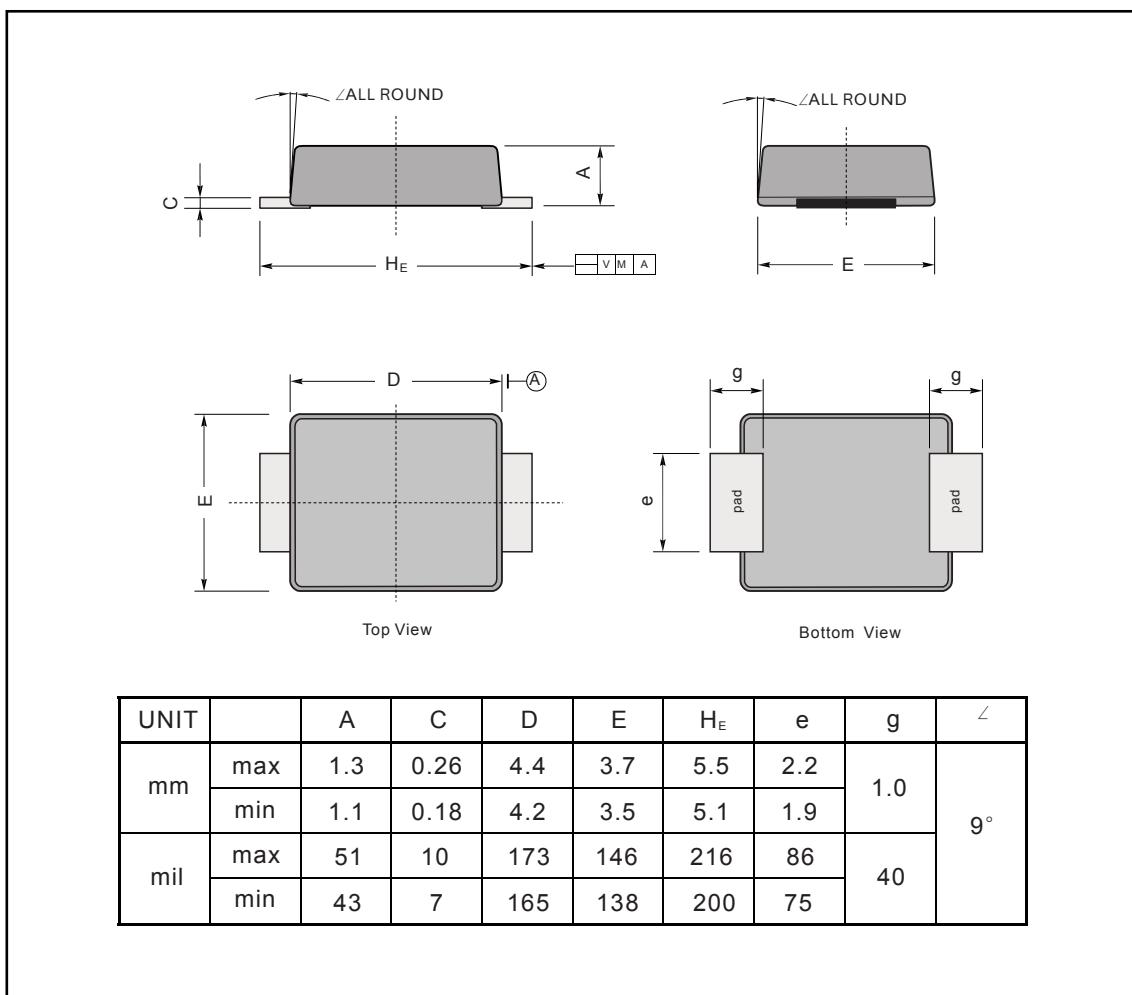
Fig.4 Maximum Non-Repetitive Peak Forward Surge Current



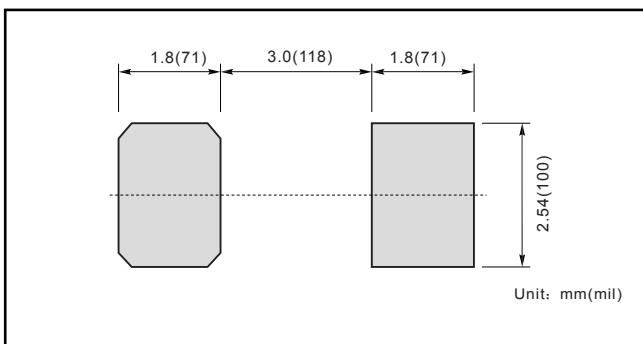
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMBF



The recommended mounting pad size



Marking

Type number	Marking code
US2ABF	U2AB
US2BBF	U2BB
US2DBF	U2DB
US2GBF	U2GB
US2JBF	U2JB
US2KBF	U2KB
US2MBF	U2MB